



PATENTS  
112055-0040

#16  
Amend  
C  
2-5-03

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Re The Application of: )  
David Chong et al. )  
Serial No.: 09/823,600 )  
Filed: March 30, 2001 )  
For: PACKAGING SYSTEM FOR )  
DIE-UP CONNECTION OF A )  
DIE-DOWN ORIENTED INTE- )  
GRATED CIRCUIT )

Examiner: Andujar, Leonardo

Art Unit: 2826

Cesari and McKenna, LLP  
88 Black Falcon Avenue  
Boston, MA 02210  
January 17, 2003

RECEIVED  
JAN 23 2003  
TECHNOLOGY CENTER 2800

Honorable Assistant Commissioner for Patents  
Washington, D.C. 20231

Sir:

**PRELIMINARY AMENDMENT**

The amendment filed November 14, 2002 is to be entered and considered as indicated on the Request for Continued Examination (RCE) Transmittal Sheet. In addition, please enter and consider this Preliminary Amendment.

The original application was restricted to claims 1-8 with original claims 9-14 reserved for a later filing, and a new apparatus claim 15 was added by amendment

Please add the following new claims:

C' --Claim 16 (new) The die attach package of claim 1 wherein the die being attached is an integrated circuit. --